

### Trench IGBT Modules

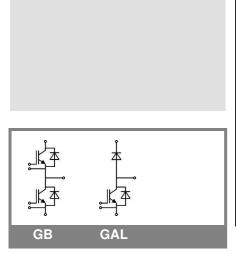
SKM 200GB176D SKM 200GAL176D

#### **Features**

- Homogeneous Si
- Trench = Trenchgate technology
- V<sub>CEsat</sub> with positive temperature coefficient
- High short circuit capability, self limiting to 6 x I<sub>c</sub>

### **Typical Applications\***

- AC inverter drives mains 575 -750 V AC
- Public transport (auxiliary syst.)



<b>Absolute Maximum Ratings</b> T <sub>c</sub> = 25 °C, unless otherwise specifie						
Symbol	Conditions		Values	Units		
IGBT						
$V_{CES}$	$T_j = 25 ^{\circ}\text{C}$ $T_i = 150 ^{\circ}\text{C}$		1700	V		
I <sub>C</sub>	T <sub>j</sub> = 150 °C	T <sub>c</sub> = 25 °C	260	Α		
		T <sub>c</sub> = 80 °C	180	Α		
I <sub>CRM</sub>	I <sub>CRM</sub> =2xI <sub>Cnom</sub>		300	Α		
$V_{GES}$			± 20	V		
t <sub>psc</sub>	$V_{CC}$ = 1200 V; $V_{GE} \le 20$ V;	T <sub>i</sub> = 125 °C	10	μs		
	V <sub>CES</sub> < 1700 V	,				
Inverse	Diode					
$I_{F}$	T <sub>j</sub> = 150 °C	$T_c = 25 ^{\circ}C$	210	Α		
		$T_c = 80  ^{\circ}C$	140	Α		
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		300	Α		
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; sin.	T <sub>j</sub> = 150 °C	1100	Α		
Freewhe	eling Diode					
$I_{F}$	T <sub>j</sub> = 150 °C	T <sub>case</sub> = 25 °C	210	Α		
		$T_{case}$ = 80 °C	140	Α		
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		300	Α		
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; sin.	T <sub>j</sub> = 150 °C	1100	Α		
Module				•		
I <sub>t(RMS)</sub>			500	Α		
T <sub>vj</sub>			- 40 <b>+</b> 150	°C		
T <sub>stg</sub>			-40+125	°C		
V <sub>isol</sub>	AC, 1 min.		4000	V		

Characteristics $T_c =$		25 °C, unless otherwise specified				
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}$ , $I_{C} = 6 \text{ mA}$		5,2	5,8	6,4	V
I <sub>CES</sub>	$V_{GE} = 0 V, V_{CE} = V_{CES}$	T <sub>j</sub> = 25 °C			3	mA
$V_{CE0}$		T <sub>j</sub> = 25 °C		1	1,2	V
		T <sub>j</sub> = 125 °C		0,9	1,1	V
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C		6,7	8,3	mΩ
		T <sub>j</sub> = 125°C		10	12	$m\Omega$
V <sub>CE(sat)</sub>	I <sub>Cnom</sub> = 150 A, V <sub>GE</sub> = 15 V			2	2,45	V
		T <sub>j</sub> = 125°C <sub>chiplev</sub> .		2,4	2,9	V
C <sub>ies</sub>				11,4		nF
C <sub>oes</sub>	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		0,55		nF
C <sub>res</sub>				0,44		nF
$Q_G$	V <sub>GE</sub> = -8V+15V			1200		nC
R <sub>Gint</sub>	T <sub>j</sub> = 25 °C			4,25		Ω
t <sub>d(on)</sub>				360		ns
t <sub>r</sub>	$R_{Gon} = 5 \Omega$	V <sub>CC</sub> = 1200V		45		ns
E <sub>on</sub>	<b>D</b> 50	I <sub>C</sub> = 150A		93		mJ
t <sub>d(off)</sub>	$R_{Goff} = 5 \Omega$	T <sub>j</sub> = 125 °C		760		ns
t <sub>f</sub>		$V_{GE} = \pm 15V$		140		ns
E <sub>off</sub>				58		mJ
R <sub>th(j-c)</sub>	per IGBT				0,12	K/W



## Trench IGBT Modules

### SKM 200GB176D SKM 200GAL176D

#### **Features**

- Homogeneous Si
- Trench = Trenchgate technology
- V<sub>CEsat</sub> with positive temperature coefficient
- High short circuit capability, self limiting to 6 x I<sub>c</sub>

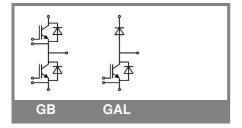
### Typical Applications\*

- AC inverter drives mains 575 -750 V AC
- Public transport (auxiliary syst.)

Characte	ristics						
Symbol	Conditions	I	min.	typ.	max.	Units	
Inverse Diode							
$V_F = V_{EC}$	$I_{Fnom} = 150 \text{ A}; V_{GE} = 0 \text{ V}$			1,7	1,9	V	
		$T_j = 125  ^{\circ}C_{\text{chiplev.}}$		1,7	1,9	V	
$V_{F0}$		T <sub>j</sub> = 25 °C		1,1	1,3	V	
		T <sub>j</sub> = 125 °C		0,9	1,1	V	
r <sub>F</sub>		T <sub>j</sub> = 25 °C		4	4	mΩ	
		T <sub>j</sub> = 125 °C		5,3	5,3	mΩ	
I <sub>RRM</sub>	I <sub>F</sub> = 150 A	T <sub>j</sub> = 125 °C		195		Α	
$Q_{rr}$	di/dt = 3700 A/μs			52		μC	
E <sub>rr</sub>	$V_{GE} = -15 \text{ V}; V_{CC} = 1200 \text{ V}$	V		31		mJ	
$R_{th(j-c)D}$	per diode				0,25	K/W	
FWD							
$V_F = V_{EC}$	$I_{Fnom}$ = 150 A; $V_{GE}$ = 0 V			1,7	1,9	V	
		$T_j = 125  ^{\circ}C_{\text{chiplev.}}$ $T_j = 25  ^{\circ}C$		1,7	1,9	V	
$V_{F0}$				1,1	1,3	V	
		T <sub>j</sub> = 125 °C		0,9	1,1	V	
r <sub>F</sub>		T <sub>j</sub> = 25 °C		4	4	V	
		T <sub>j</sub> = 125 °C		5,3	5,3	V	
I <sub>RRM</sub>	I <sub>F</sub> = 150 A	T <sub>j</sub> = 125 °C		195		Α	
$Q_{rr}$	di/dt = 3700 A/µs			52		μC	
E <sub>rr</sub>	$V_{GE} = -15 \text{ V}; V_{CC} = 1200 \text{ V}$	V		31		mJ	
$R_{th(j-c)FD}$	per diode				0,25	K/W	
Module							
L <sub>CE</sub>				15	20	nΗ	
R <sub>CC'+EE'</sub>	res., terminal-chip	T <sub>case</sub> = 25 °C		0,35		mΩ	
		T <sub>case</sub> = 125 °C		0,5		mΩ	
R <sub>th(c-s)</sub>	per module				0,038	K/W	
M <sub>s</sub>	to heat sink M6		3		5	Nm	
M <sub>t</sub>	to terminals M6		2,5		5	Nm	
w					325	g	

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

\* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.





OLIMITTIANO 0

Trench IGBT Modules

SKM 200GB176D SKM 200GAL176D

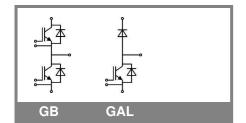
Eggti	iroc

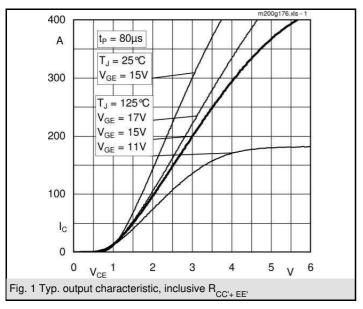
- · Homogeneous Si
- Trench = Trenchgate technology
- V<sub>CEsat</sub> with positive temperature coefficient
- High short circuit capability, self limiting to 6 x I<sub>c</sub>

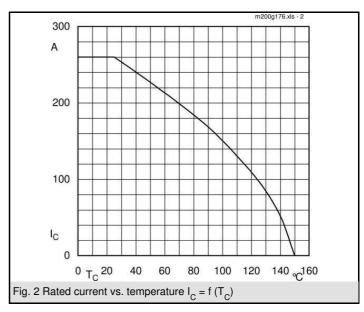
### **Typical Applications\***

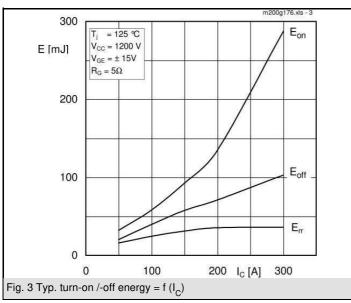
- AC inverter drives mains 575 -750 V AC
- Public transport (auxiliary syst.)

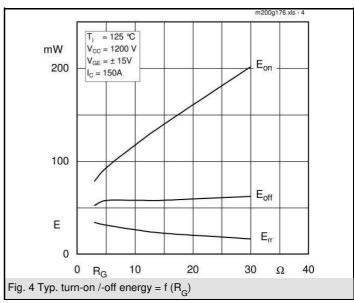
Z <sub>th</sub>			
Symbol	Conditions	Values	Units
Z,,,,,,,,			
Z <sub>th(j-c)l</sub>	i = 1	80	mk/W
R <sub>i</sub>	i = 2	30	mk/W
Ri	i = 3	8,2	mk/W
R <sub>i</sub>	i = 4	1,8	mk/W
tau <sub>i</sub>	i = 1	0,0753	s
tau <sub>i</sub>	i = 2	0,01	s
tau <sub>i</sub>	i = 3	0,0008	s
tau <sub>i</sub>	i = 4	0,0003	s
Z <sub>th(j-c)D</sub>			
R <sub>i</sub>	i = 1	160	mk/W
R <sub>i</sub>	i = 2	67	mk/W
$R_i$	i = 3	20	mk/W
$R_i$	i = 4	3	mk/W
tau <sub>i</sub>	i = 1	0,0382	s
tau <sub>i</sub>	i = 2	0,009	s
tau <sub>i</sub>	i = 3	0,0009	s
tau <sub>i</sub>	i = 4	0,005	s

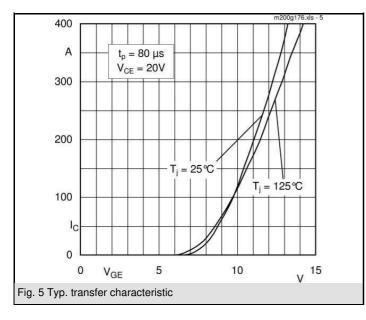


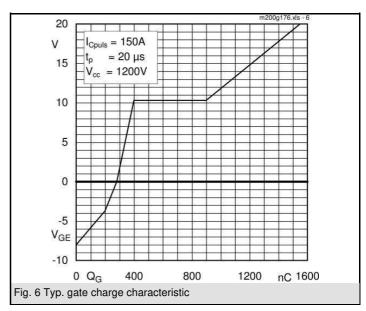


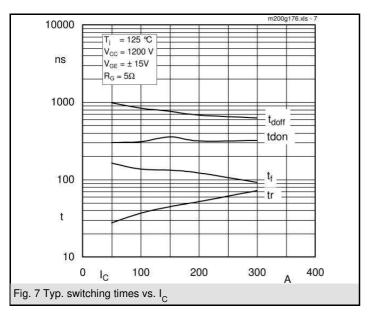


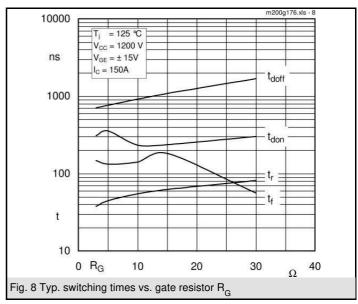


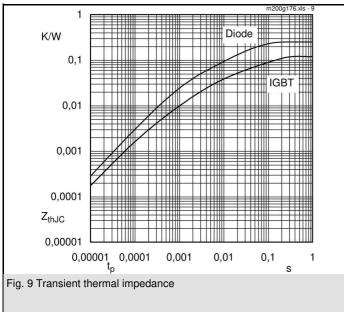


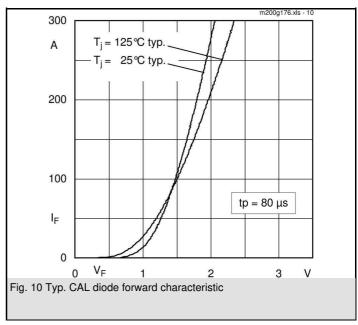


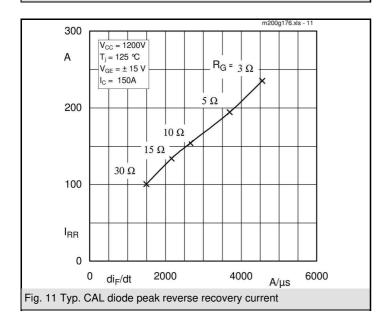


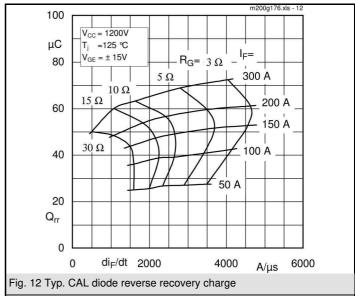


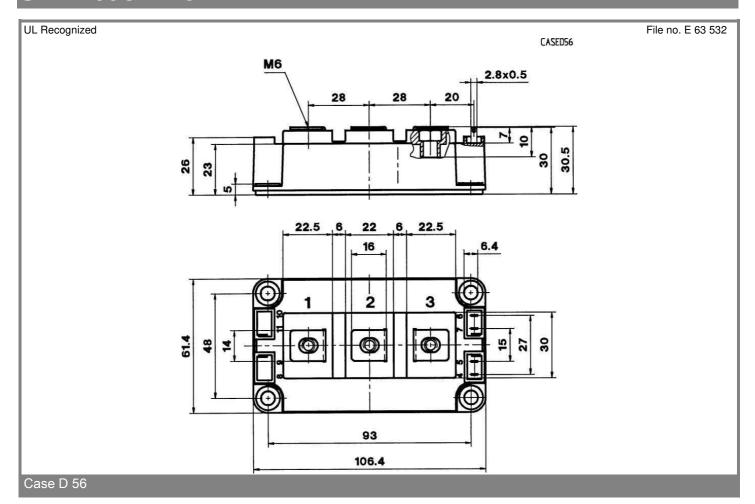


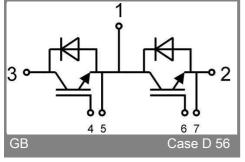


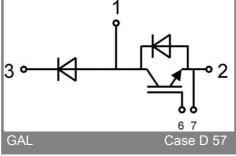












6 28-06-2010 GIL © by SEMIKRON